

CLAIMS

1. A method for manufacturing a pad conditioner, comprising:
 - depositing a photosensitive film on a base substrate, followed by etching to form a plurality of receiving holes in the photosensitive film;
 - inserting abrasive grains into the receiving holes and then filling the receiving holes by primary plating to form a filling layer;
 - blanketing a plating layer over all of the photosensitive film, the filling layer, and the abrasive grains by secondary plating; and
 - removing the base substrate, the photosensitive film, and the filling layer to expose a part of each of the abrasive grains.
2. The method of claim 1, wherein the plating layer into which the abrasive grains are partially embedded is attached to a conditioner substrate using an adhesive.
3. The method of claim 1, wherein the filling layer and the plating layer are made of different respective materials.
4. A pad conditioner, manufactured by the method of claim 1, wherein a plurality of abrasive grains protrudes from the plating layer at a uniform height, and the plating layer has a convex portion at a boundary to the abrasive grains.
5. A method for manufacturing a pad conditioner, comprising:
 - depositing a photosensitive film on a base substrate, followed by etching to form a plurality of receiving holes in the photosensitive film,
 - inserting abrasive grains into the receiving holes and then filling the receiving holes by primary plating to form a filling layer;
 - removing the photosensitive film;
 - conducting a secondary plating process to form a support layer for covering the upper surface of the base substrate and portions side-walls of the abrasive grains;
 - blanketing a plating layer over all the support layer and the abrasive grains by

tertiary plating;

removing the base substrate, and then the support layer and the filling layer to expose a part of each of the abrasive grains.

6. The method of claim 5, wherein the plating layer into which the abrasive grains are partially embedded is attached to a conditioner substrate using an adhesive.

7. The method of claim 5, wherein the support layer and the filling layer are made of a same material.

8. The method of claim 5, wherein the plating layer is different in material from the support layer and the filling layer.